



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC010N04LSI	<b>Issued</b>	03. June 2021
<b>MA#</b>	MA005425566		
<b>Package</b>	PG-TDSON-8-26	<b>Weight*</b>	115.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.32	1.32	13157	13157
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		449	
	non noble metal	copper	7440-50-8	51.740	44.87	44.92	448677	449261
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	389	389
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		702	
	plastics	epoxy resin	-	6.394	5.54		55446	
	inorganic material	silicondioxide	60676-86-0	33.993	29.48	35.09	294779	350927
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12067	12067
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1681	1681
solder	non noble metal	tin	7440-31-5	0.042	0.04		365	
	noble metal	silver	7440-22-4	0.053	0.05		456	
	non noble metal	lead	7439-92-1	2.010	1.74	1.83	17434	18255
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.635	0.55		5511	
	non noble metal	copper	7440-50-8	17.131	14.86	15.42	148558	154263
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com